

115-3821 Plating Solution, Gold, 1 oz (.03 liter)

Electroplating solution for gold surfaces and gold edge contacts. This solution is ideally suited for plating printed circuit board edge contacts and other conductive surfaces. Gold plating solution used for edge contact repair and replating must be highly concentrated. This highly concentrated gold plating solution has a ratio of .03125 troy ounce of gold per fluid ounce. This solution does not contain free cyanide.

The solution may be used with any suitable plating equipment. The normal voltage applied when plated is between four and nine volts. Anodes may be constructed from stainless steel, platinum, titanium, or graphite/carbon.



NOTE: Prices are subject to change without notice based on gold market prices.

Classifications

Harmonize Code	3824.90.7000
Export Administration Regulations (EAR)	EAR99
Export Control Classification Number (ECCN)	Not Applicable